Notes:

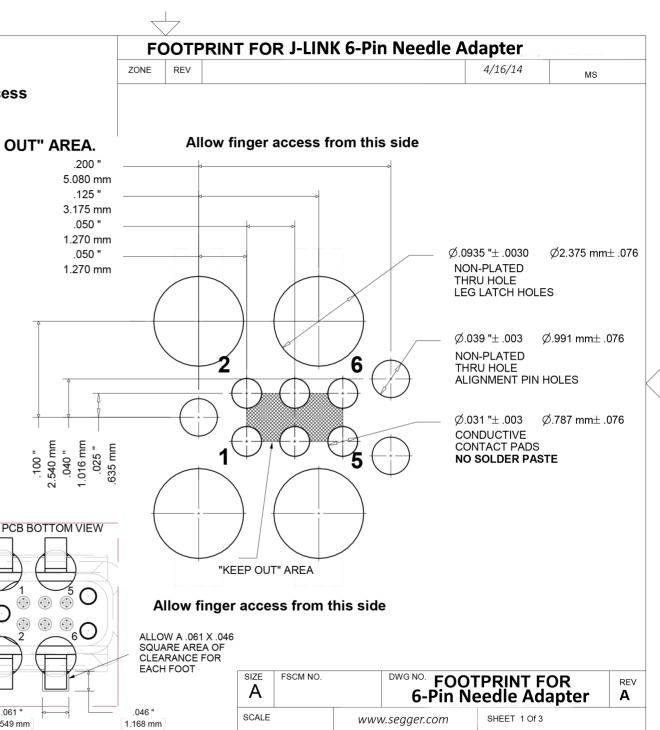
- 1. Allow clearance for finger squeeze access from the two sides shown
- 2. No tracks or vias in the shaded "KEEP OUT" AREA.

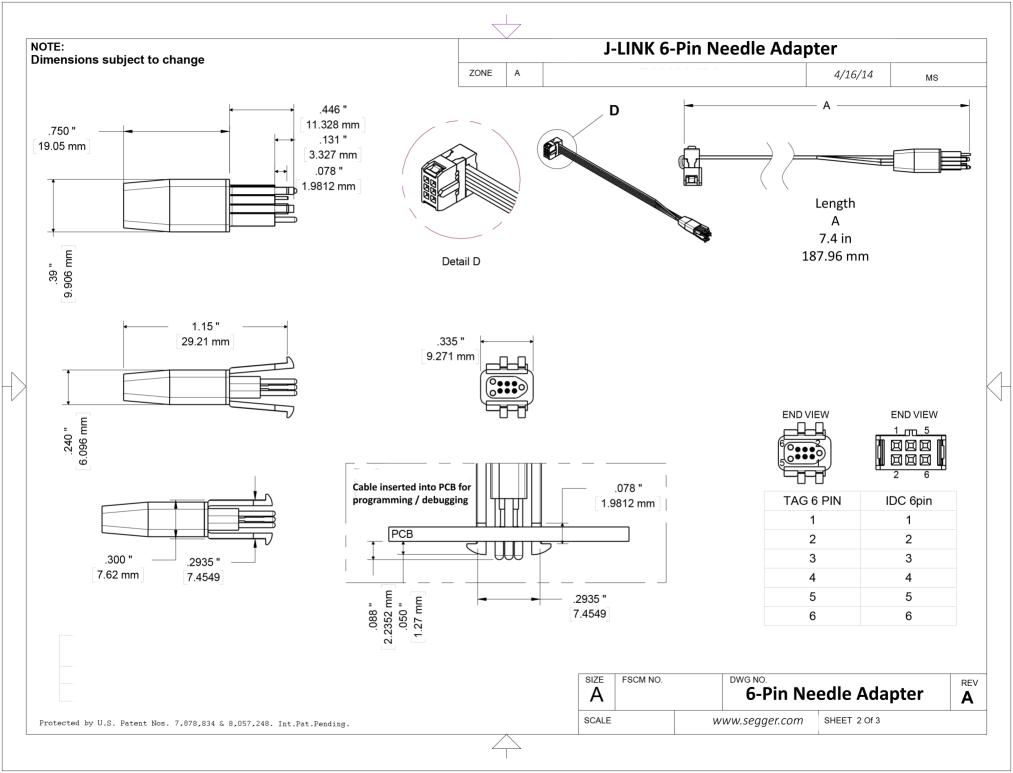
100 "

.061

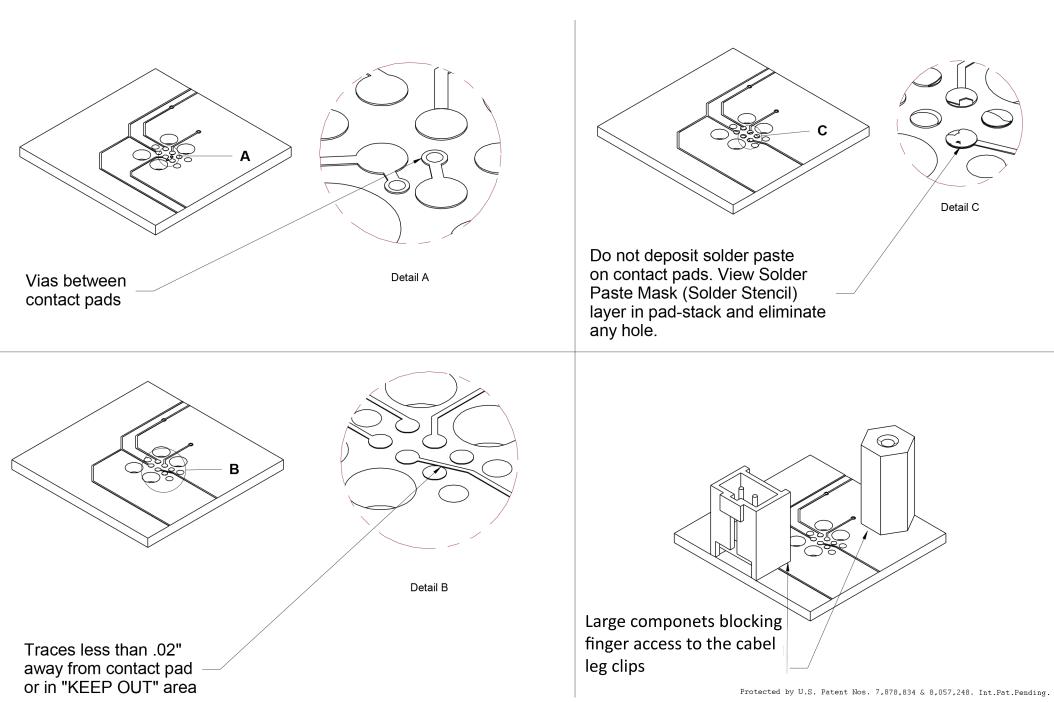
- 3. No other track or signal within .02" of any contact pad.
- 4. Do not allow solder paste on the contact pads It is essential to eliminate any hole in the solder paste-mask (solder stencil) laver. If this is not possible make the contact pads thru-hole with a finished hole size of .008" or less.
- 5. Leg and alignment holes may be plated and used as vias but ensure minimum finshed hole size meets specified tolerances.
- 6. To prevent purchasing confusion. please specify DNL in your BOM.
- 7. If using a proto-board fab that plates all through holes, make sure all holes are defined as plated in the footprint.

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Layout Problems to Avoid



Mouser Electronics

Authorized Distributor

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Segger Microcontroller: <u>8.06.16</u>